

CLAIMS:

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1. A process for forming a semiconductor product, comprising the steps of:  
providing a semiconductor substrate having a semiconductor surface;  
introducing N-type dopant impurities into said semiconductor surface, thereby  
forming N-doped regions within said semiconductor surface;  
introducing nitrogen into at least one of said N-doped regions to form at least one  
10 nitrogen region; and,  
thermally oxidizing said substrate surface to form an oxide film on said  
semiconductor surface, said oxide film having a first thickness in said at least one  
nitrogen region and a second thickness being greater than said first thickness in other  
portions of said N-doped regions.
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2. The process as in claim 1, in which said semiconductor product is a Metal  
Oxide Semiconductor (MOS) capacitor and in which each nitrogen region forms a  
capacitor region and further comprising forming a top capacitor plate of one of a  
conductive material and a semiconductor material over each capacitor region, after said  
20 step of thermally oxidizing.
3. The process as in claim 1, in which said step of introducing nitrogen  
comprises ion implantation.
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4. The process as in claim 3, in which said step of introducing nitrogen  
includes an implant energy within the range of 5-9 keV and an implant dosage which  
lies within the range of  $10^{14}/\text{cm}^2$  to  $10^{15}/\text{cm}^2$ .
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5. The process as in claim 1, in which said step of thermally oxidizing  
includes forming said oxide film having said first thickness being less than 50% of said  
second thickness.
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6. The process as in claim 1, in which said first thickness is less than 55  
angstroms and said second thickness lies within the range of 80-150 angstroms.

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7. The process as in claim 1, in which said step of introducing N-type dopant  
impurities includes forming said N-doped regions to include an N-type impurity  
5 concentration which lies within the range of  $10^{18}/\text{cm}^3$  to  $10^{19}/\text{cm}^3$ .

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8. The process as in claim 1, in which said nitrogen region includes a  
nitrogen density within the range of  $10^{17}$  to  $10^{19}/\text{cm}^3$ .

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9. The process as in claim 1, in which semiconductor surface regions in  
which said N-type dopant impurities are not introduced, are designated undoped  
regions, and said step of thermally oxidizing includes forming said oxide film having a  
third thickness in said undoped regions, said third thickness being less than 50% of said  
second thickness.

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10. The process as in claim 1, further comprising the step of defining said at  
least one nitrogen region prior to said step of introducing nitrogen, said defining  
comprising forming a masking pattern in a photosensitive material.

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11. The process as in claim 10, in which said masking pattern includes each  
nitrogen region forming a lower capacitor electrode, having a rectangular shape and  
including sides ranging from 2 to 100 microns in length.

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12. The process as in claim 1, wherein said thermally oxidizing comprises  
furnace oxidation at a temperature ranging from  $750^\circ\text{C}$  to  $950^\circ\text{C}$ , for a time ranging  
from 5 to 15 minutes.

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13. The process as in claim 1, wherein said N-type dopant impurity comprises  
one of phosphorous and arsenic.

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14. The process as in claim 1, in which said step of introducing nitrogen  
comprises introducing nitrogen into at least one entire N-doped region of said N-doped  
regions.

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15. The process as in claim 1, in which said step of introducing nitrogen includes introducing nitrogen into a first portion of a designated N-doped region, a second portion of said designated N-doped region not having nitrogen introduced therein.

16. The process as in claim 1, wherein said semiconductor substrate comprises silicon and said oxide film comprises silicon dioxide.

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sub A4 > 17. A process for forming a thermal oxide film having multiple thicknesses, comprising the steps of:  
providing a silicon substrate having a silicon surface;  
forming a plurality of dopant impurity regions in said silicon surface, said dopant impurity regions formed of one of phosphorous and arsenic;  
15 implanting nitrogen into a nitrogen portion of at least one of said dopant impurity regions; and  
thermally oxidizing said substrate to form an oxide film thereover, said oxide film having a first thickness in said nitrogen portions and a second thickness in other portions of said dopant impurity regions, said second thickness being greater than said first thickness by at least 80%.

18. The process as in claim 17, in which said step of thermally oxidizing includes forming said oxide film having a third thickness in undoped regions of said silicon surface, said third thickness and said first thickness being substantially equal.

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sub A5 > 19. A process for forming a Metal Oxide Semiconductor (MOS) capacitor, comprising the steps of:  
providing a silicon substrate having a silicon surface;  
30 introducing N-type dopant impurities into said silicon surface, thereby forming N-doped regions within said silicon surface;  
implanting nitrogen into at least one of said N-doped regions to form at least one capacitor region;  
thermally oxidizing said substrate to form an oxide film on said silicon surface,  
35 said oxide film having a first thickness in said at least one capacitor region and a

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second thickness being greater than said first thickness in other portions of said N-doped regions; and,

forming a top capacitor plate of at least one of a conductive material and a semiconductor material over said at least one capacitor region.

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20. A semiconductor product including a capacitor formed over an N-type impurity region of a semiconductor substrate, said capacitor comprising an upper electrode, a lower electrode formed of a capacitor portion of said N-type impurity region which further includes nitrogen therein, and a dielectric interposed between said upper and lower electrodes, said dielectric including nitrogen therein.

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21. The semiconductor product as in claim 20, in which said capacitor portion of said N-type impurity region includes a nitrogen concentration within a range of  $10^{17}/\text{cm}^3$  to  $10^{19}/\text{cm}^3$ , and said N-type impurity region includes an N-type dopant impurity concentration ranging from  $10^{18}/\text{cm}^3$  to  $10^{19}/\text{cm}^3$ .

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22. The semiconductor product as in claim 20, in which said semiconductor substrate comprises silicon and said dielectric film comprises a thermal oxide film further extending over further portions of said N-type impurity region and over bulk portions of said silicon substrate in which N-type impurities are not present, said thermal oxide film characterized by having a first thickness in said capacitor region being less than a second thickness over said further portions of said N-type impurity region, and a third thickness over said bulk portions being substantially the same as said first thickness.

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23. The semiconductor product as in claim 20, in which said dielectric film is a continuous film which further extends over further portions of said N-type impurity region and over bulk portions of said substrate in which N-type impurities are not present, said dielectric film characterized by the absence of nitrogen in regions other than said capacitor region.

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24. The semiconductor product as in claim 23, wherein said dielectric film comprises a thermal oxide film.

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25. A semiconductor product including a capacitor formed over a silicon substrate and including a lower electrode formed of a region of said silicon substrate including nitrogen and N-type impurities therein.

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